

Abstract of the Disclosure:

The device has a package with a base plate, and at least two terminal pins perpendicularly protruding from the base plate of the package. At least one of the terminal pins is a high-frequency terminal pin that transmits a high-frequency signal. The device has a flexible conductor arrangement with a plurality of interconnects. The conductor arrangement provides an electrical connection between the terminal pins of the package and electrical contacts of a printed circuit board. The conductor arrangement has contact regions for electrically connecting the interconnects to a terminal pin and to a contact of a printed circuit board. At least the region of the conductor arrangement that provides a connection to high-frequency terminal pin lies in a plane aligned substantially perpendicular to the plane of the base plate.